

Notice of References Cited	Application/Control No. 10/028,610	Applicant(s)/Patent Under Reexamination OMSTEAD ET AL.	
	Examiner Matthew J Song	Art Unit 1765	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-6,143,082	11-2000	McInerney et al.	118/719
	C	US-6,143,128	11-2000	Ameen et al.	156/345.24
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	E	US-4,545,136	10-1985	Izu et al.	34/636
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Rossnagel et al. "Plasma enhanced atomic layer deposition of Ta and Ti for interconnect diffusion barriers", Jul/Aug 2000, J. Va. Sci. Technol. B 18(4), pp 2016-2020.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.